

SL-SMT 5.08HC/04/270GL 1.5SN BK BX**Weidmüller Interface GmbH & Co. KG**

Klingenbergstraße 26

D-32758 Detmold

Germany

www.weidmueller.com

Product image

High-temperature-resistant, straight, open pin header.
Packed in box or tape. On tape and with 1.5 mm solder pin, optimised for automatic assembly. 3.2 mm solder pin suitable for reflow and wave soldering. The pin headers provide space for labelling and can be coded. HC = High Current.

General ordering data

Version	PCB plug-in connector, male header, closed side, THT/THR solder connection, 5.08 mm, Number of poles: 4, 270°, Solder pin length (l): 1.5 mm, tinned, black, Box
Order No.	1877140000
Type	SL-SMT 5.08HC/04/270GL 1.5SN BK BX
GTIN (EAN)	4032248467594
Qty.	100 pc(s).
Product data	IEC: 400 V / 27.5 A UL: 300 V / 18.5 A
Packaging	Box

Creation date September 16, 2022 8:36:21 PM CEST

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Technical data**Dimensions and weights**

Depth	12 mm	Depth (inches)	0.472 inch
Height	10 mm	Height (inches)	0.394 inch
Height of lowest version	8.5 mm	Width	23.52 mm
Width (inches)	0.926 inch	Net weight	2.33 g

System specifications

Product family	OMNIMATE Signal - series BL/SL 5.08	Type of connection	Board connection
Mounting onto the PCB	THT/THR solder connection	Pitch in mm (P)	5.08 mm
Pitch in inches (P)	0.2 inch	Outgoing elbow	270°
Number of poles	4	Number of solder pins per pole	1
Solder pin length (l)	1.5 mm	Solder pin length tolerance	0 / -0.3 mm
Solder pin dimensions	d = 1.2 mm, Octagonal	Solder eyelet hole diameter (D)	1.4 mm
Solder eyelet hole diameter tolerance (D)+ 0,1 mm		L1 in mm	15.24 mm
L1 in inches	0.6 inch	Number of rows	1
Pin series quantity	1	Touch-safe protection acc. to DIN VDE 57 106	finger-safe plugged/ back-of-hand-safe unplugged
Touch-safe protection acc. to DIN VDE 0470	IP20 plugged/ IP10 unplugged	Protection degree	IP20
Volume resistance	≤5 mΩ	Can be coded	Yes
Plugging force/pole, max.	9 N	Pulling force/pole, max.	7 N

Material data

Insulating material	LCP GF	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	IIIa
Comparative Tracking Index (CTI)	≥ 175	Moisture Level (MSL)	1
UL 94 flammability rating	V-0	Contact material	CuMg
Contact surface	tinned	Layer structure of solder connection	1...3 µm Ni / 2...4 µm Sn matt
Layer structure of plug contact	1...3 µm Ni / 2...4 µm Sn matt	Storage temperature, min.	-40 °C
Storage temperature, max.	70 °C	Operating temperature, min.	-50 °C
Operating temperature, max.	100 °C	Temperature range, installation, min.	-30 °C
Temperature range, installation, max.	100 °C		

Rated data acc. to IEC

tested acc. to standard	IEC 60664-1, IEC 61984	Rated current, min. number of poles (Tu=20°C)	27.5 A
Rated current, max. number of poles (Tu=20°C)	19 A	Rated current, min. number of poles (Tu=40°C)	24 A
Rated current, max. number of poles (Tu=40°C)	16.5 A	Rated voltage for surge voltage class / pollution degree II/2	400 V
Rated voltage for surge voltage class / pollution degree III/2	320 V	Rated voltage for surge voltage class / pollution degree III/3	250 V
Rated impulse voltage for surge voltage class/ pollution degree II/2	4 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	4 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	4 kV		

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Technical data**Rated data acc. to CSA**

Institute (CSA)



Certificate No. (CSA)

200039-1176845

Rated voltage (Use group B / CSA) 300 V

Rated voltage (Use group D / CSA) 300 V

Rated current (Use group B / CSA) 18.5 A

Rated current (Use group D / CSA) 18.5 A

Reference to approval values
Specifications are maximum values, details - see approval certificate.**Packing**

Packaging Box

VPE length 169 mm

VPE width 118 mm

VPE height 38 mm

Classifications

ETIM 6.0 EC002637

ETIM 7.0 EC002637

ETIM 8.0 EC002637

ECLASS 9.0 27-44-04-02

ECLASS 9.1 27-44-04-02

ECLASS 10.0 27-44-04-02

ECLASS 11.0 27-46-02-01

ECLASS 12.0 27-46-02-01

Important note

IPC conformity

Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.

Notes

- Gold-plated contact surfaces on request
- Rated current related to rated cross-section & min. No. of poles.
- Diameter of solder eyelet D = 1.4+0.1mm
- Solder eyelet diameter D = 1.5 + 0.1 mm, from 9 poles
- P on drawing = pitch
- Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards.
- Long term storage of the product with average temperature of 50 °C and average humidity 70%, 36 months

Approvals

Approvals



ROHS Conform

UL File Number Search UL Website

Certificate No. (UR) E60693

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Technical data

Downloads

Approval/Certificate/Document of Conformity	Declaration of the Manufacturer
Engineering Data	CAD data – STEP
Catalogues	Catalogues in PDF-format
Brochures	FL DRIVES EN
	MB SMT EN
	FL DRIVES DE
	MB DEVICE MANUF. EN
	FL BUILDING SAFETY EN
	FL APPL LED LIGHTING EN
	FL INDUSTR.CONTROLS EN
	FL MACHINE SAFETY EN
	FL HEATING ELECTR EN
	FL APPL INVERTER EN
	FL_BASE_STATION_EN
	FL ELEVATOR EN
	FL POWER SUPPLY EN
	FL 72H SAMPLE SER EN
White paper surface mount technology	PO OMNIMATE EN
	PO OMNIMATE EN
Download Whitepaper	

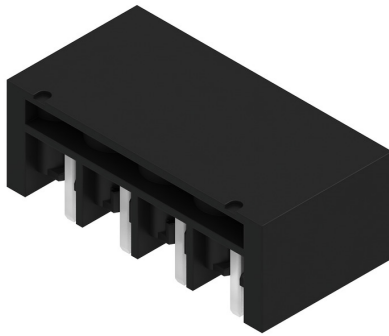
SL-SMT 5.08HC/04/270GL 1.5SN BK BX

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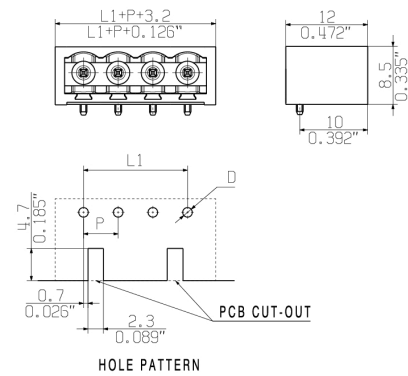
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Drawings

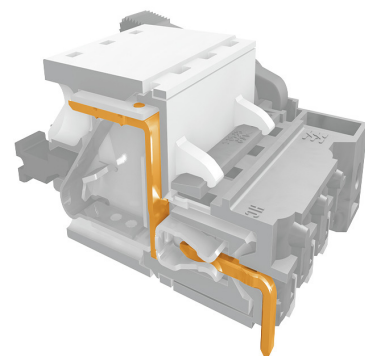
Product image



Dimensional drawing



Product benefits



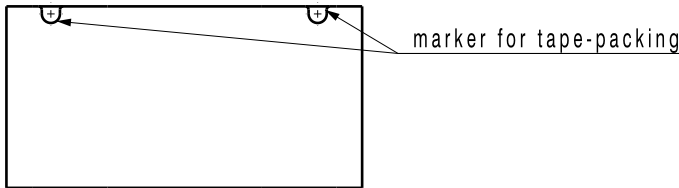
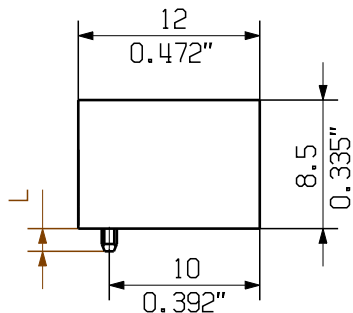
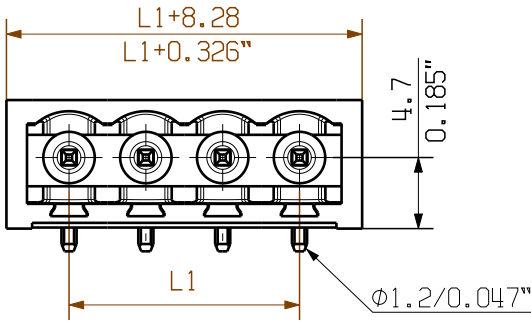
Safe power transmission
Proven properties

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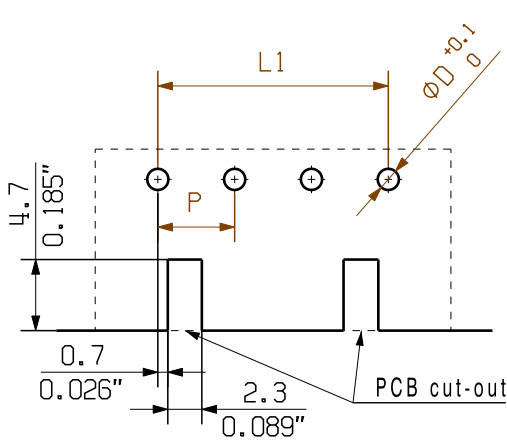
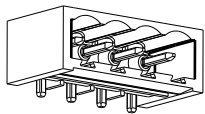
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Dimensions without tolerances are no check dimensions

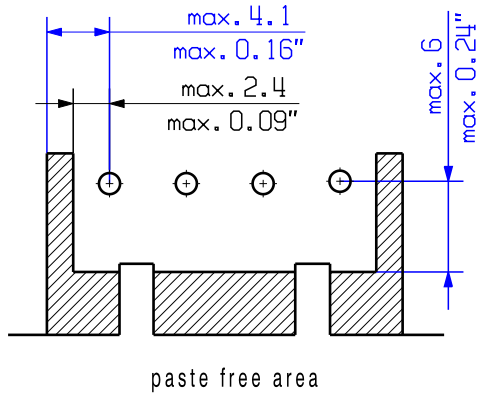
The English version is binding



1:1



hole pattern



paste free area

For the mounting of PCBs, it should be noted that the rated data given in the catalogue relates only to the connection elements. The necessary creepage and clearance paths must be observed in connection with the respective applicant in accordance to VDE 0110. The current-carrying capacity and pitch tolerance is to be determined according to DIN IEC 326 part 3 very fine.

1,5	0
	-0.3
3,2	0.1
	-0.3
pin lenght L	tolerance

Weidmüller connectors are tested to the DIN VDE 0627 standard, and are valid for its field of application. Provided that the connectors are used to the intended purpose, all requirements with respect to the occurring of electrical, mechanical, thermic and corrosive stress will be satisfied.

D=1.4/0.055" (reflow soldering)
recommendation for automatic assembly
(1.4mm for n=2...8)

P= Pitch

shown: SL-SMT 5.08HC/04/270GL

8	35,56	1,400	±0.1
7	30,48	1,200	
6	25,40	1,000	
5	20,32	0,800	
4	15,24	0,600	
3	10,16	0,400	
2	5,08	0,200	
n	L1 [mm]	L1 [Inch]	tolerance L1

GENERAL TOLERANCE:
DIN ISO 2768-m



91033/4
03.02.17 HERTEL_S 00

Modification

Weidmüller



Cat.no.: .

3 37899

17

Drawing no.

Issue no.

Sheet 01

of 06 sheets



Date	Name
Drawn 23.03.2004	DOMRATH_M
Responsible	HERTEL_S
Checked 06.02.2017	HELIS_MA
Approved	LANG_T

SL-SMT 5.08HC/.. /270...
STIFTLISTE
MALE HEADER

Scale: 2/1

Supersedes: .

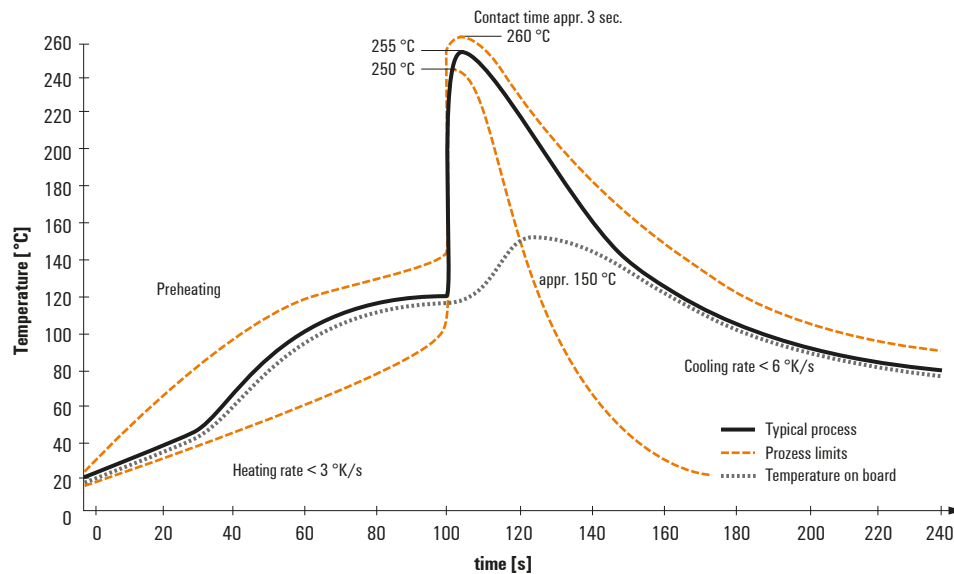
Product file: SL-SMT 5.08

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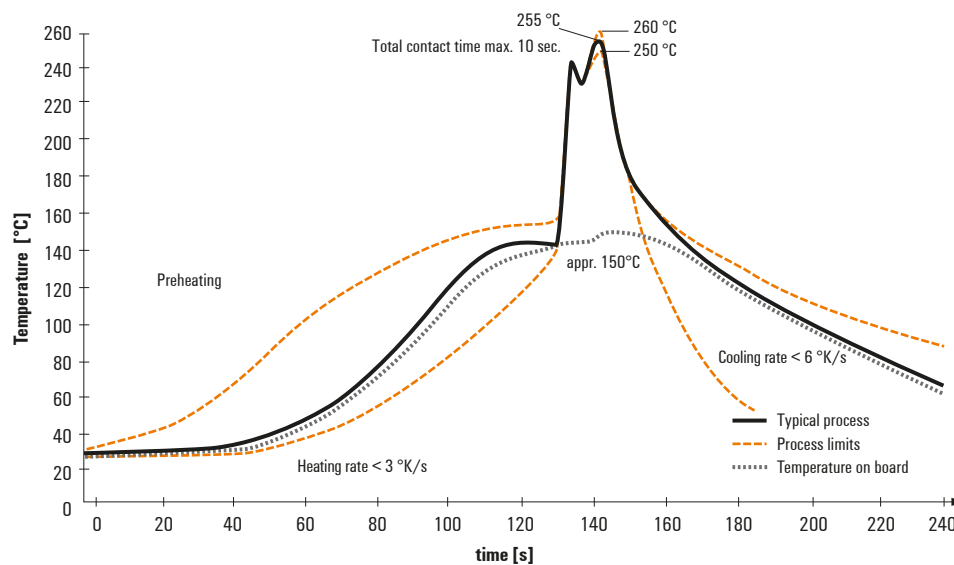
Recommended wave soldering profiles

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 16
D-32758 Detmold
Germany
Fon: +49 5231 14-0
Fax: +49 5231 14-292083
www.weidmueller.com

Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

We reserve the right to make technical changes.

Recommended reflow soldering profile

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 16
D-32758 Detmold
Germany
Fon: +49 5231 14-0
Fax: +49 5231 14-292083
www.weidmueller.com



Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.